	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen
1	BRS	L1		1 [	kanakasabapathy near sivananda.in.	16 17 19	2004/11/ 18 13:58	
2	BRS	L2		0	sarma noar	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 13:58	
3	BRS	L3		0	fishkill near Ihar.in.	US- PGPU B; USPA T; EPO; DERW ENT; IBM_ TDB	2004/11/ 18 13:58	

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen
4	BRS	L4		65	hummel near john.in.	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 13:59	
5	BRS	L5		1/1	gaidis near michael.in.	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 14:00	
6	BRS	L7		470	438/401.ccls.	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 14:02	

	Type	L	#	Hits	Search Text	DBs	Time Stamp	Commen
7	BRS	L8		144		US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 14:03	
8	BRS	L9		5	(metaliz\$5) near25 (opening or hole or	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:16	
9	BRS	L1	0	12	(mark\$1) near25 (metaliz\$5) near25 (opening or hole or aperture or via or recess or sti)	US- PGPU B; USPA T; EPO; DERW ENT; IBM_ TDB	2004/11/ 18 14:12	

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen
10	BRS	L1	1	1	(mark\$1) near25 (opening or hole or	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 14:13	
11	BRS	L1	2	872		1	2004/11/ 18 14:14	
12	BRS	L1	3		(mark\$1) near25 (opening or hole or aperture or via or recess or sti) near25 (metal\$6) near25 (pattern\$3 or etch\$3)	1	2004/11/ 18 14:45	1 .

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen ts
13	BRS	L1	4	0	(mark\$1) near25 (opening or hole or aperture or via or recess or sti) near25 (lower near	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 14:46	
14	BRS	L1	5	872			2004/11/ 18 14:47	
15	BRS	L1	6	619.	(mark\$1) near25 (opening or hole) near25 (metal\$6)	US- PGPU B; USPA T; EPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:16	

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen ts
16	BRS	L1	7	0	(mtj) near25 (metaliz\$5) near25 (opening or hole or aperture or via or	EPO;	2004/11/ 18 15:19	
17	BRS	L1	.8	0	tunnel near	JPO;	2004/11/ 18 15:23	
18	BRS	L1	.9	35	junction) near25 (metal\$7) near25 (opening or hole or	US- PGPU B; USPA T; EPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:18	

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen ts
19	BRS	L2	0	53	(mtj) near25 (metal\$7) near25 (opening or hole or aperture or via or recess or sti)	1	2004/11/ 18 15:22	
20	BRS	L2	1	0	<pre>(mtj) near25 (metal\$7) near25 (opening or hole or aperture or via or recess or sti)</pre>	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:26	
21	BRS	L2	2	0	(opening or hole or aperture or via or recess or sti) near25 (mark\$1)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:22	

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen
22	BRS	L23	3	35	(magnetic near tunnel near junction) near25 (metal\$7) near25 (opening or hole or aperture or via or	EPO; JPO;	2004/11/ 18 15:24	
23	BRS	L2	4	0	(magnetic near tunnel near junction) near25 (mark\$1) near25 (opening or hole or aperture or via or	DPO;	2004/11/ 18 15:24	
24	BRS	L2:	5	0	tunnel near junction) same ((mark\$1) near25 (opening or hole or aperture or via or recess or sti))	1	2004/11/ 18 15:24	

	Туре	L #	Hits	Search Text	DBs	Time Stamp	Commen
25	BRS	L26	1	(magnetic near tunnel near junction) near25 (mark\$1)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:25	
26	BRS	L27	2	(mtj) near25 (mark\$1)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:27	
27	BRS	L28	8332	(opaque near layer)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:27	

	Туре	L #	Hits	Search Text	DBs	Time Stamp	Commen ts
28	BRS	L29		(opaque near layer) near25 (metal\$7) near35 (mark\$1)	US- PGPU B; USPA T; EPO; DERW ENT; IBM_ TDB	2004/11/ 18 15:28	·

	U	1	PT	P	Document ID	Issue Date	Page s	Title
1					US 2004004064 8 A1	20040304		Method for replicating optical elements, particularly on a wafer level, and replicas formed thereby
2					US 2003001188 9 A1	20030116	1	Wafer level creation of multiple optical elements
3				,	US 2003001043 1 A1	20030116		Method of mass producing and packaging integrated subsystems
4				-	US 2001003270 2 A1	20011025	14	Method of mass producing and packaging integrated optical subsystems
5					US 6649008 B2	20031118	14	Method of mass producing and packaging integrated subsystems
6					US 6610166 B1	20030826	12	Method for replicating optical elements, particularly on a wafer level, and replicas formed thereby
7					US 6451150 B2	20020917	13	Method of mass producing and packaging integrated optical subsystems

	<b>ט</b> ַ	1	PT	P	D	ocument ID	Issue Date	Page s	Title
8					US B1	6406583	20020618		Wafer level creation of multiple optical elements
9					US B1	6235141	20010522	13	Method of mass producing and packaging integrated optical subsystems
10					US A	6096155	20000801	111	Method of dicing wafer level integrated multiple optical elements
11					US A	5815292	19980929	5	Low cost diffraction images for high security application
12					US A	3731005	19730501	9	LAMINATED COIL